News Release



Teledyne Scientific Presenting Three New Papers Next Week at

International Microwave Symposium 2019

Teledyne authors presenting their findings at three sessions, "Emerging mm-Wave Transistor Technologies for 5G and DoD Applications," "mm-Wave and THz Power Amplifiers," and "Advances in CMOS, and HBT Technologies for Monolithic ICs"

RANCHO CORDOVA, CA – May 30, 2019 – Next week at the annual International Microwave Symposium (IMS) trade show in Boston, Teledyne Scientific staff will be taking part in three of the Technical Sessions being held on Thursday, June 6. The three Teledyne Scientific staff people presenting technical papers at the sessions will be Keisuke Shinohara, Principal Scientist, Zach Griffith, mm-wave and THz Design and Product Engineer, and Andrea Arias, Senior RF Engineer.

These papers showcase Teledyne's leadership in linear broadband millimeter-Wave amplifiers with high efficiency. Teledyne Scientific will also be present during the show at the <u>Teledyne Defense Electronics</u> (TDE), Booth #1124 where they will be featuring their mmWave InP power amplifiers which deliver some of the highest bandwidth and efficiency from 30 to 300 GHz.

Dr. Shinohara will be presenting first during the technical session entitled "**Emerging mm-Wave Transistor Technologies for 5G and DoD Applications.**"

- Paper being presented: "GaN-Based Multi-Channel Transistors with Lateral Gate for Linear and Efficient Millimeter-Wave Power Amplifiers."
- Authors:
 K. Shinohara, C. King, E.J. Regan, Josh Bergman, Andrew D. Carter, Andrea Arias, Miguel Urteaga, Bobby Brar, R. Page, R. Chaudhuri, M. Islam, H. Xing, D. Jena
- **Time:** 9:00 to 9:20 am, Thursday, June 6
- Session: Th1F-4 Place: 254AB

Dr. Griffith will be presenting next during the technical session entitled "mm-Wave and THz Power Amplifiers."

• Paper being presented:

"A 140-GHz 0.25-W PA and a 55–135GHz 115–135mW PA: High-Gain, Broadband Power Amplifier MMICs in 250-nm InP HBT"

- Authors: Zach Griffith, Miguel Urteaga, Petra Rowell
- **Time:** 10:10 to 10:30 am, Thursday, June 6
- Session: Th2D-1 Place: 157BC

Ms. Arias will make the final presentation during the session entitled "Advances in CMOS, and HBT Technologies for Monolithic ICs."

• Paper being presented: "185mW InP HBT Power Amplifier with 1 Octave Bandwidth (25-50GHz), 38% Peak PAE at 44 GHz and Chip

Area of 276x672µm²"

• Authors:

Andrea Arias, Petra Rowell, Miguel Urteaga, Zach Griffith, K. Shinohara, Josh Bergman, Andrew D. Carter, Richard Pierson, Bobby Brar, James F. Buckwalter, Mark J.W. Rodwell

• Time: 11:30 to 11:50 am, Thursday, June 6

• Session: Th2F-6 Place: 254AB

To learn more about the presentations and read Abstracts of the papers being presented, visit the IMS website section on <u>Technical Sessions</u>.

In addition to Teledyne Scientific, other Teledyne companies participating in TDE Booth #1124 include <u>Teledyne</u> <u>e2v Semiconductors</u>, <u>Teledyne e2v RF Power -- Defence</u>, <u>Teledyne Labtech</u>, <u>Teledyne Microwave Solutions</u> (RF & Microwave Products), <u>Teledyne MEC</u> (TWT Products), <u>Teledyne Relays</u> / <u>Teledyne Coax Switches</u> and <u>Teledyne Storm Microwave</u>.

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